Application Note

UCC2808A-xQ1Functional Safety FIT Rate and FMD

Table of Contents

1 Overview 2
2 Functional Safety Failure In Time (FIT) Rates 3
3 Failure Mode Distribution (FMD) 4
4 Pin Failure Mode Analysis (Pin FMA) 5
5 Revision History 6

1 Overview

This document contains information for UCC2808A-xQ1 (SOIC 8 package) to aid in a functional safety system design. Information provided are:

- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device

Figure 1-1 shows the device functional block diagram for reference.

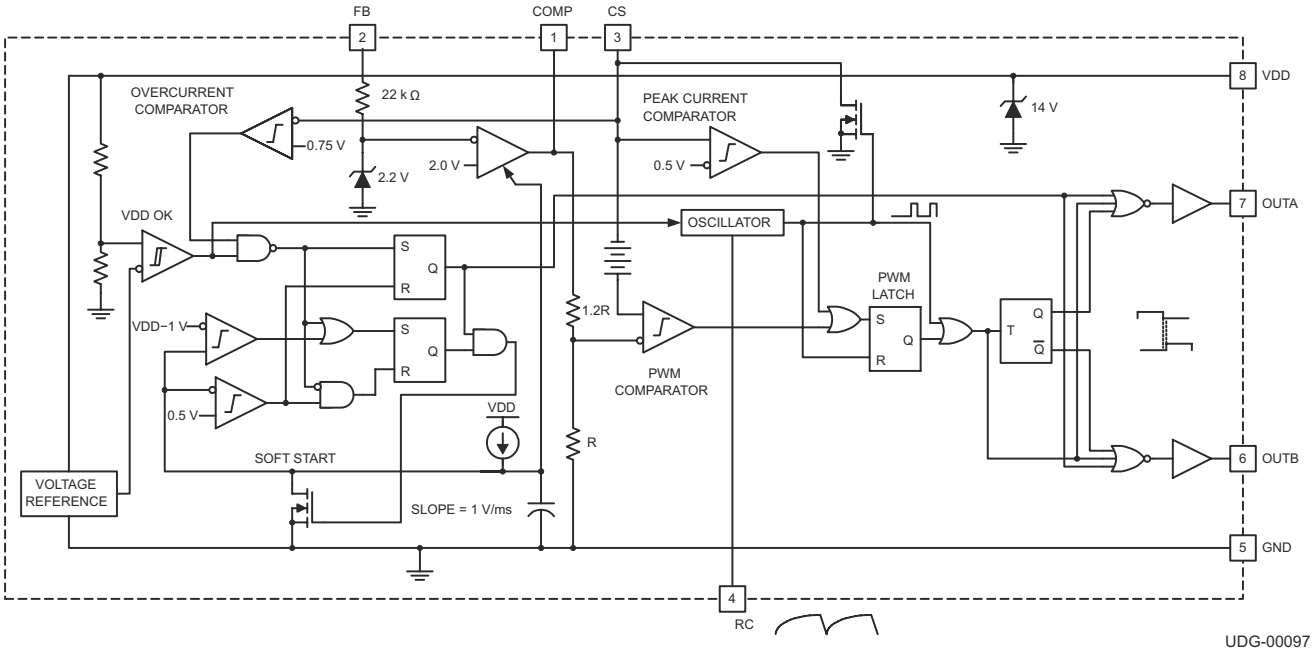

Figure 1-1. Functional Block Diagram

UCC2808A-xQ1 was developed using a quality-managed development process, but was not developed in accordance with the IEC 61508 or ISO 26262 standards.

2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for UCC2808A-xQ1 based on two different industry-wide used reliability standards:

- Table 2-1 provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- Table 2-2 provides FIT rates based on the Siemens Norm SN 29500-2

Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10^9 Hours)
Total Component FIT Rate (75mW, 150mW, 300mW)	10, 11, 15
Die FIT Rate (75mW, 150mW, 300mW)	3, 4, 7
Package FIT Rate (75mW, 150mW, 300mW)	7, 7, 8

The failure rate and mission profile information in Table 2-1 comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 75 mW, 150 mW, 300 mW
- Climate type: World-wide Table 8
- Package factor (lambda 3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2

Table	Category	Reference FIT Rate	Reference Virtual T_J
5	CMOS, BICMOS Digital, analog / mixed	20 FIT	55°C

The Reference FIT Rate and Reference Virtual T_J (junction temperature) in Table 2-2 come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for UCC2808A-xQ1 in Table 3-1 comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

Table 3-1. Die Failure Modes and Distribution

Die Failure Modes	Failure Mode Distribution (%)
OUTA and OUTB stuck low	15
OUTA and OUTB pulse width not as expected	13
OUTA stuck low	12
OUTA stuck high	12
OUTB stuck low	12
OUTB stuck high	12
System is unstable	5
No effect	19

4 Pin Failure Mode Analysis (Pin FMA)

This section provides a Failure Mode Analysis (FMA) for the pins of the UCC2808A-xQ1(SOIC 8). The failure modes covered in this document include the typical pin-by-pin failure scenarios:

- Pin short-circuited to Ground (see Table 4-2)
- Pin open-circuited (see Table 4-3)
- Pin short-circuited to an adjacent pin (see Table 4-4)
- Pin short-circuited to supply (see Table 4-5)

Table 4-2 through Table 4-5 also indicate how these pin conditions can affect the device as per the failure effects classification in Table 4-1.

Table 4-1. TI Classification of Failure Effects

Class	Failure Effects
A	Potential device damage that affects functionality
B	No device damage, but loss of functionality
C	No device damage, but performance degradation
D	No device damage, no impact to functionality or performance

Figure 4-1 shows the UCC2808A-xQ1(SOIC 8) pin diagram. For a detailed description of the device pins please refer to the *Pin Configuration and Functions* section in the UCC2808A-xQ1 data sheet.

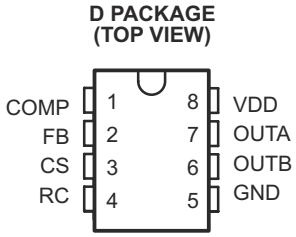

Figure 4-1. Pin Diagram

Following are the assumptions of use and the device configuration assumed for the pin FMA in this section:

- UCC2808A-xQ1 is connected according to the datasheet Figure 2 Typical application diagram.

Table 4-2. Pin FMA for Device Pins Short-Circuited to Ground

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
COMP	1	No output	B
FB	2	OUTA and OUTB operate with maximum duty cycle. Converter output can't regulate.	C
CS	3	OUTA and OUTB operate with maximum duty cycle. Converter output can't be regulated.	C
RC	4	No output.	B
GND	5	No impact.	D
OUTB	6	OUTB stays low. Device damage is possible.	A
OUTA	7	OUTA stays low. Device damage is possible.	A
VDD	8	IC is not biased. No output.	B

Table 4-3. Pin FMA for Device Pins Open-Circuited

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
COMP	1	COMP pin voltage is unstable. OUTA and OUTB duty cycle unstable. Converter output voltage oscillates.	C
FB	2	COMP voltage stays high. OUTA and OUTB operate with maximum duty cycle. Converter output voltage can't be regulated.	C

Table 4-3. Pin FMA for Device Pins Open-Circuited (continued)

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
CS	3	COMP voltage stays high. OUTA and OUTB operate with maximum duty cycle. Converter output voltage can't be regulated.	C
RC	4	No output.	B
GND	5	Converter operation is unpredictable. IC damaage is possible.	A
OUTB	6	Converter operates as a Forward converter. Converter output might not be regulated.	C
OUTA	7	Converter operates as a Forward converter. Converter output might not be regulated.	C
VDD	8	IC is not biased.	B

Table 4-4. Pin FMA for Device Pins Short-Circuited to Adjacent Pin

Pin Name	Pin No.	Shorted to	Description of Potential Failure Effect(s)	Failure Effect Class
COMP	1	FB	Converter output loses regulation.	C
FB	2	CS	OUTA and OUTB operate with maximum duty cycle. Converter output loses regulation.	C
CS	3	RC	No output.	B
RC	4	N/A	N/A	N/A
GND	5	OUTB	OUTB stays low. IC damage is possible.	A
OUTB	6	OUTA	OUTA and OUTB stay low. IC damage is possible.	A
OUTA	7	VDD	OUTA stays high. IC damage is possible	A
VDD	8	N/A	N/A	N/A

Table 4-5. Pin FMA for Device Pins Short-Circuited to supply

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
COMP	1	OUTA and OUTB operate with maximum duty cycle. IC damage is possible.	A
FB	2	OUTA and OUTB stay low. IC damage is possible.	A
CS	3	OUTA and OUTB stay low. IC damage is possible.	A
RC	4	OUTA and OUTB stay low. IC damage is possible.	A
GND	5	IC is not biased. OUTA and OUTB stay low.	B
OUTB	6	OUTB stays high. IC damage is possible.	A
OUTA	7	OUTA stays high. IC damage is possible.	A
VDD	8	No effect.	D

5 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

DATE	REVISION	NOTES
September 2021	*	Initial release

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265